

1 / 7

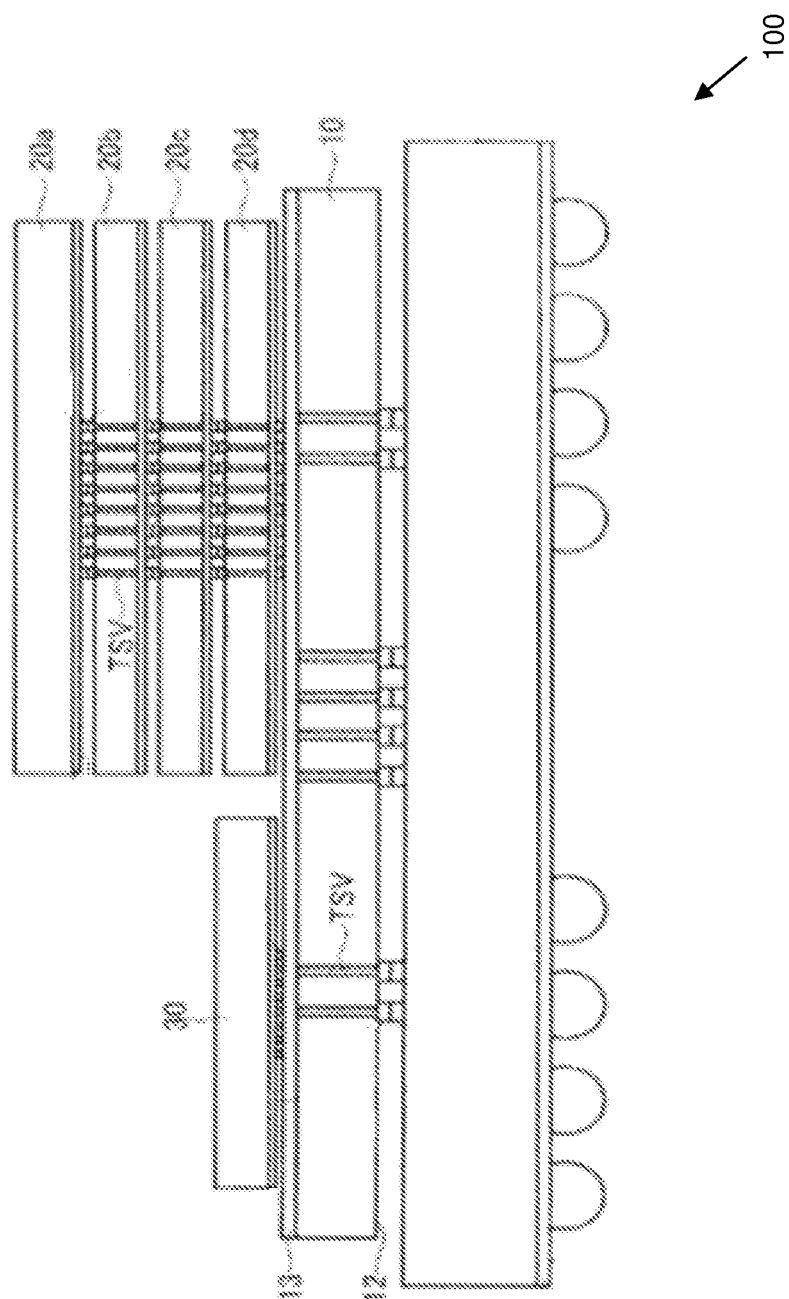


FIG. 1

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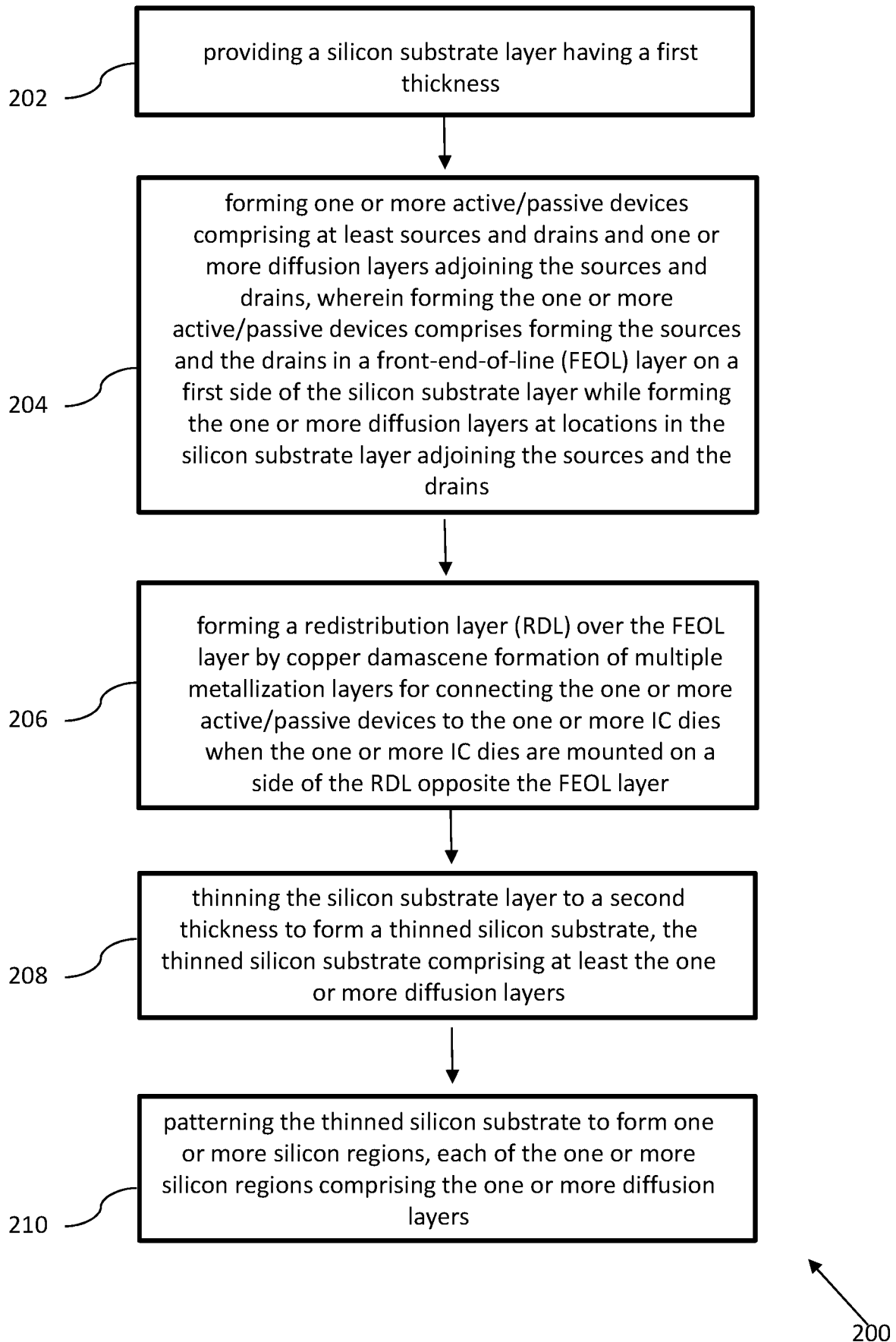


FIG. 2

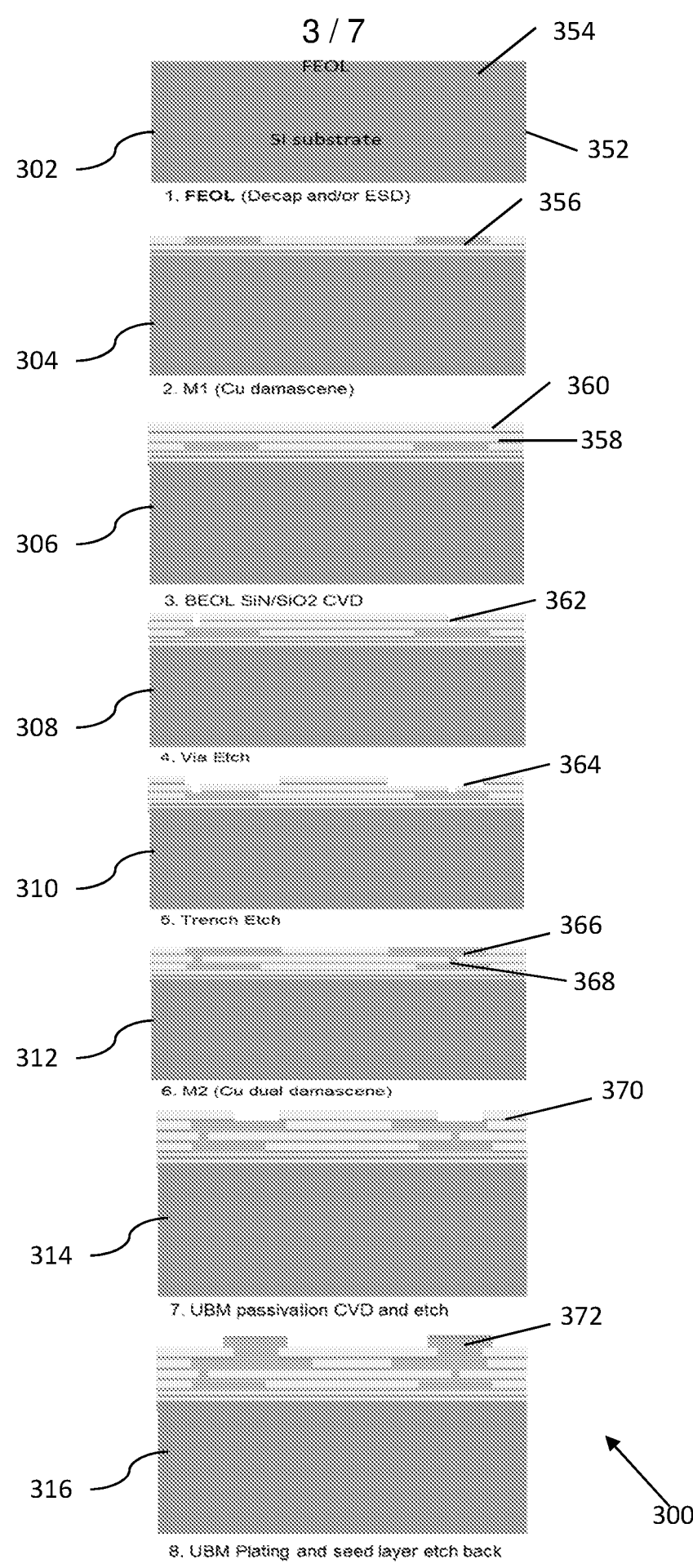


FIG. 3

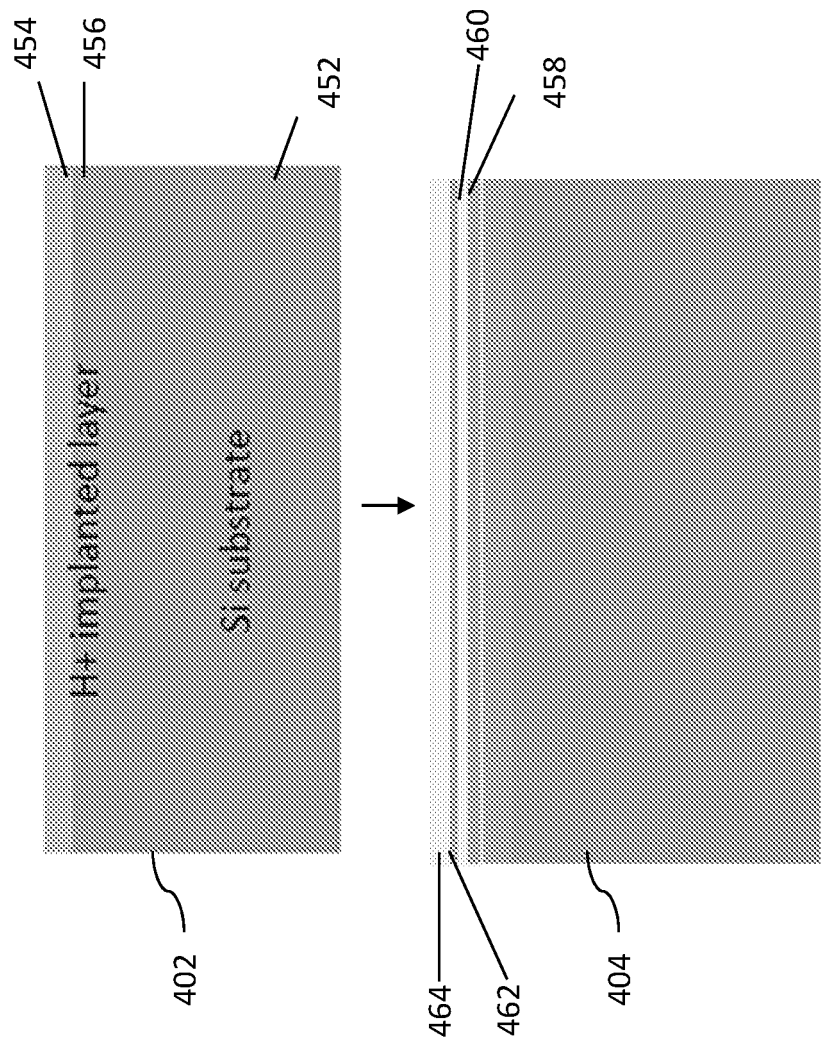
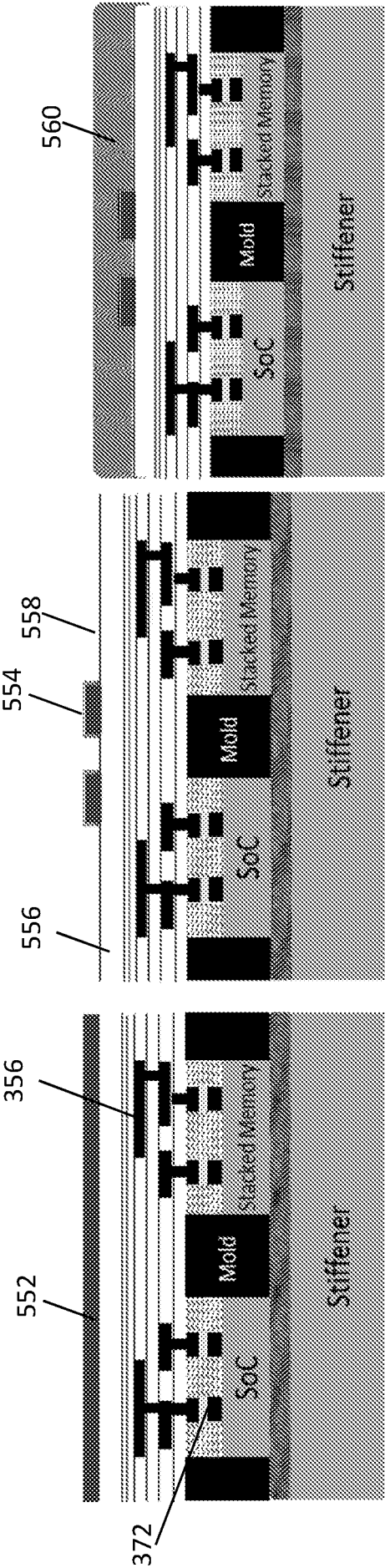
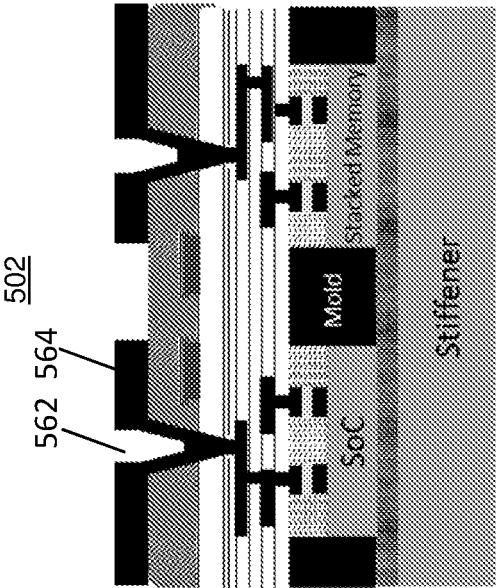


FIG. 4

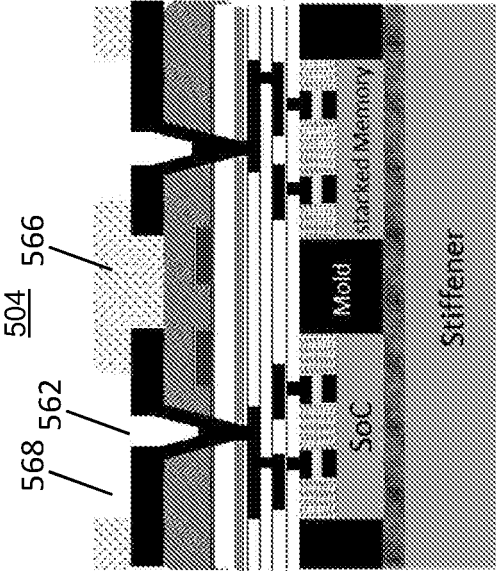


1. BG+CMP or Cleaving of Si Substrate



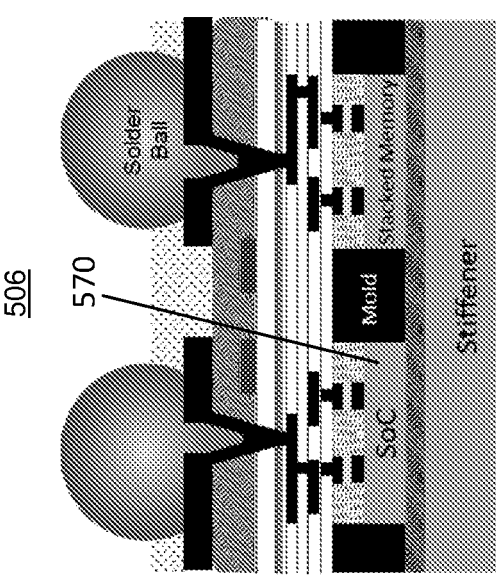
4. Opening / Cu RDL plating

2. PR + Si dry etching + SiN Passivation



5. SR coating / Opening

3. Polymer buffer layer coating / curing



6. Ball placement / Reflow



FIG. 5

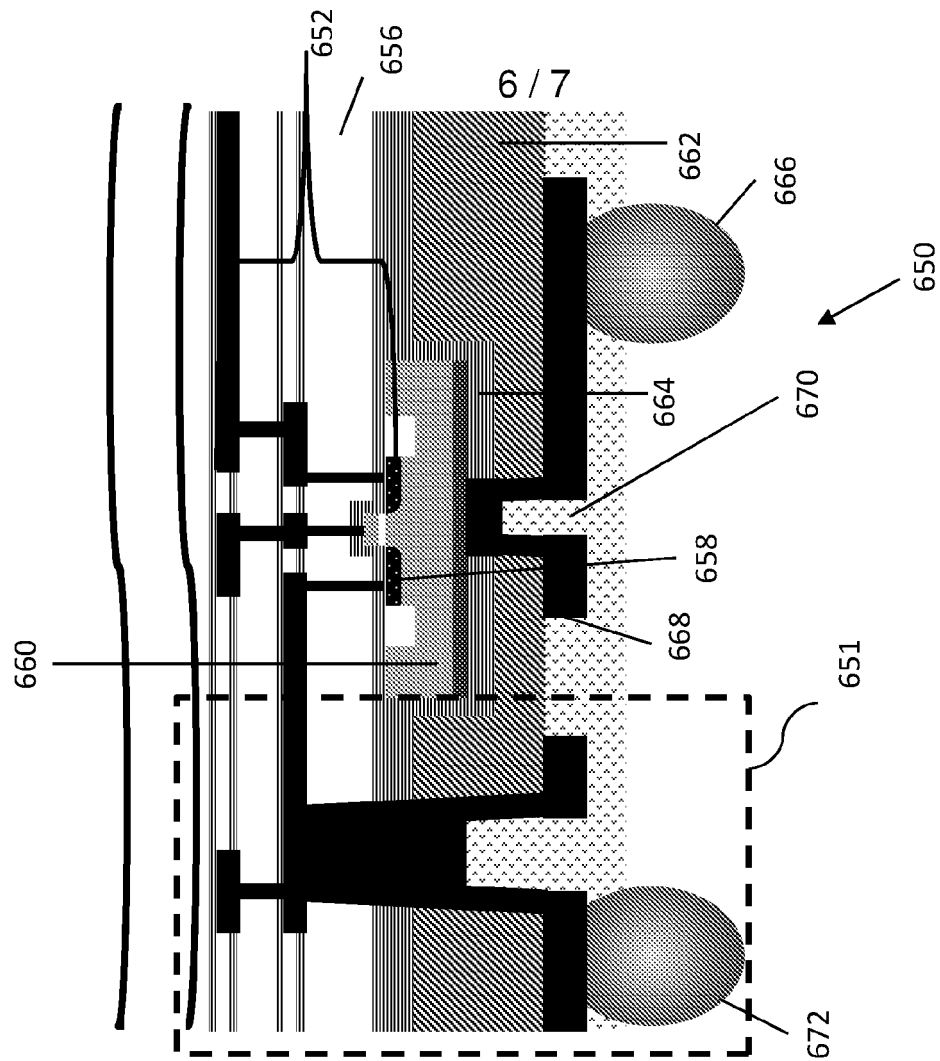


FIG. 6B

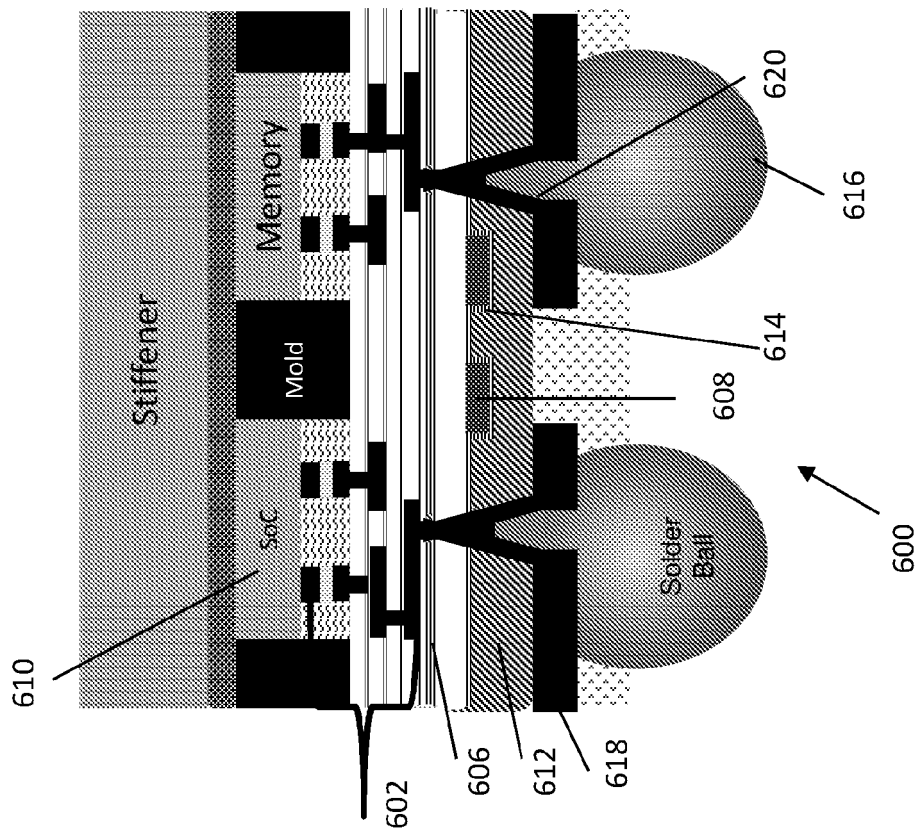


FIG. 6A

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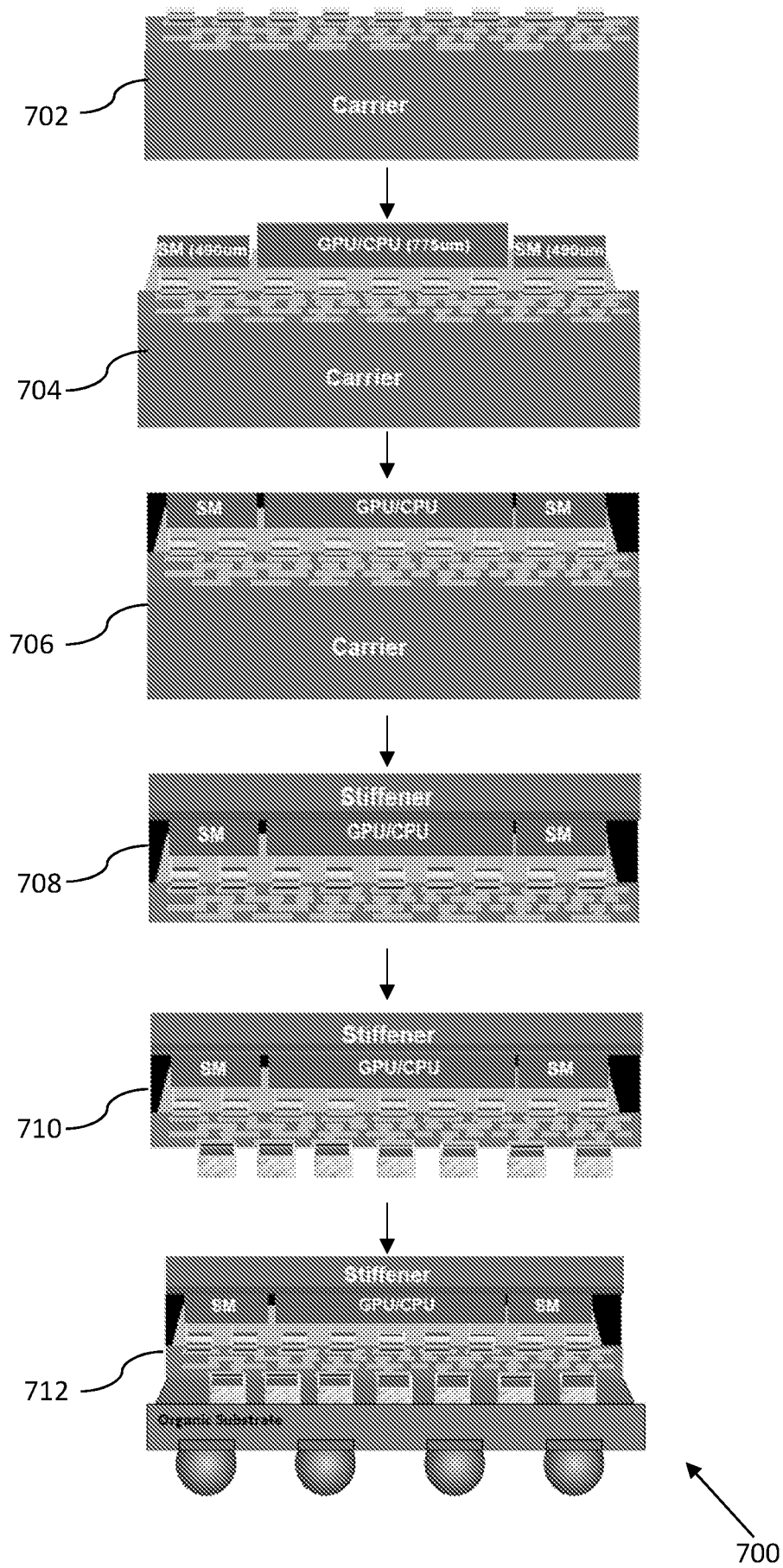


FIG. 7